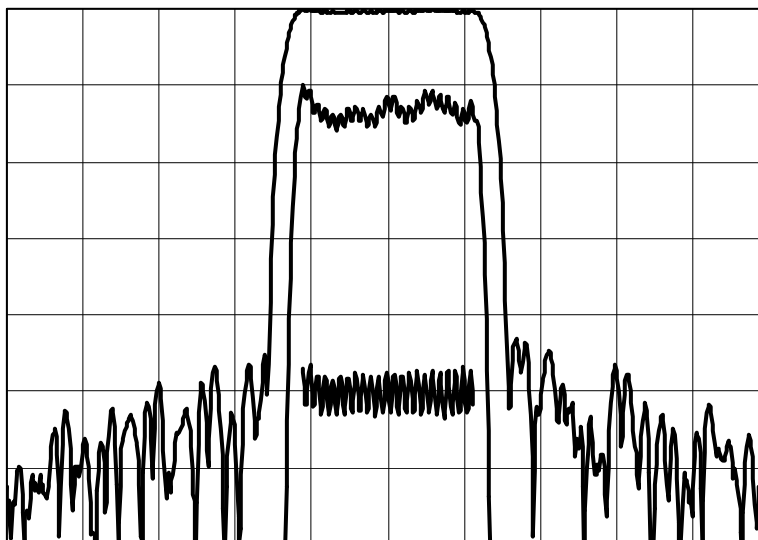


## TYPICAL PERFORMANCE



Horizontal: 2.5 MHz/div

Vertical (from top):

Magnitude 10 dB/div  
 Magnitude 1 dB/div  
 Group Delay Deviation 150 ns/div

## SPECIFICATION

Parameter	Min	Typ	Max	Units
<b>All electrical specifications apply over the full -10°C to +50°C operating range and include allowance for all manufacturing tolerances</b>				
Center Frequency $F_C$ <sup>1</sup>	114.88	115	115.12	MHz
1 dB Bandwidth <sup>2</sup>	5.6	6.08		MHz
3 dB Bandwidth <sup>2</sup>	6.0	6.44		MHz
40 dB Bandwidth <sup>2</sup>		7.75	8.2	MHz
Stopband Rejection, 25 MHz to 100 MHz	45	58		dB
Stopband Rejection, 130 MHz to 1000 MHz	45	53		dB
Minimum Insertion Loss		18.9	20	dB
Passband Amplitude Variation, $F_C \pm 2.8$ MHz <sup>3</sup>		0.6	0.8	dB p-p
Passband Group Delay Variation, $F_C \pm 2.8$ MHz		100	150	ns p-p
Absolute Delay		2.0	2.1	μs
Input VSWR, $F_C \pm 2.8$ MHz <sup>4</sup>		1.55	1.8	: 1
Output VSWR, $F_C \pm 2.8$ MHz <sup>4</sup>		1.3	1.8	: 1
Maximum Input Level	20			dBm
Source and Load Impedance		50		Ω
Operating Temperature Range	-10		+50	°C
Storage Temperature Range	-45		+85	°C

### Notes:

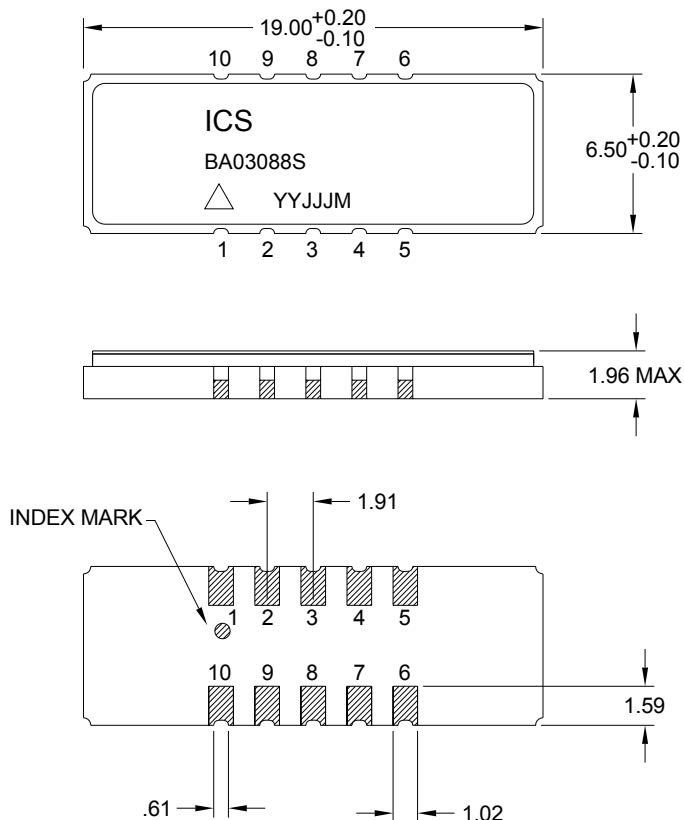
1. Defined as the mean of the 10dB frequencies.
2. dB levels are taken to be relative to the insertion loss.
3. Excludes final roll-offs to the 1dB points. Note that 'Passband Amplitude Variation' includes Ripple (fast variations) and Slope (slow variations).
4. When matched as indicated on Page 3.

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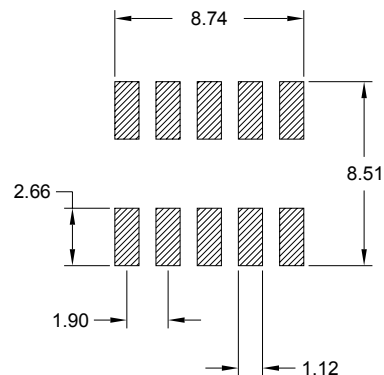
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## PACKAGE AND SUGGESTED PCB FOOTPRINT

### PACKAGE INFORMATION



### SUGGESTED PCB FOOTPRINT

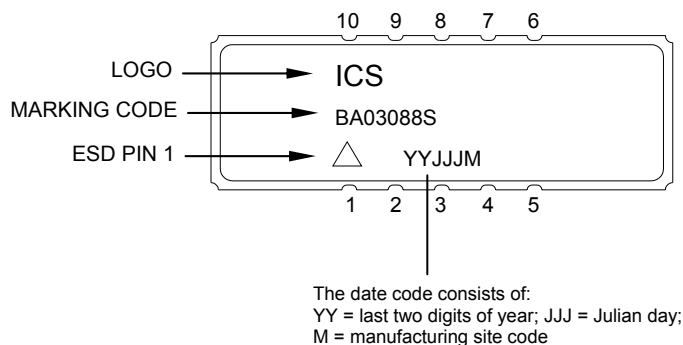


PIN NO.	DESCRIPTION
10	INPUT
5	OUTPUT
1,2,3,4,6,7,8,9	GROUND

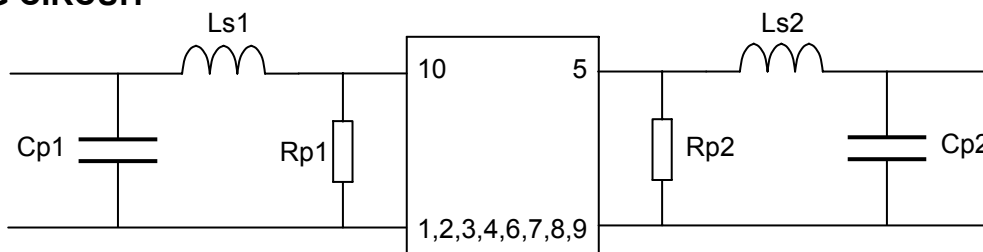
**NOTES:**  
 DIMENSIONS SHOWN ARE NOMINAL IN MILLIMETERS. ALL TOLERANCES ARE  $\pm 0.15$ MM EXCEPT OVERALL LENGTH AND WIDTH

**Package Material:**  
 Body:  $Al_2O_3$  ceramic  
 Lid: Kovar, Ni plated  
 Terminations: Au plating 0.5-1.0  $\mu$ m, over a 2-6  $\mu$ m Ni plating

## MARKING



## MATCHING CIRCUIT



Component values in 50Ω:      Rp1 = 430 Ω      Ls1 = 68 nH      Cp1 = 56 pF  
 (Minimum inductor Q = 45)      Rp2 = 300 Ω      Ls2 = 68 nH      Cp2 = 56 pF

### Notes:

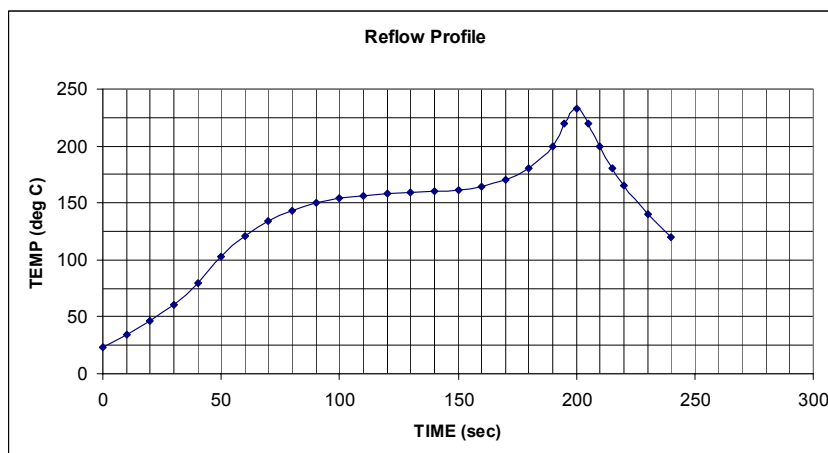
1. Optimum values may differ from these when using a different fixture or board layout. The values shown here are intended as a guide only.
2. Required component tolerances – resistors  $\pm 5\%$ , inductors  $\pm 2\%$ , capacitors  $\pm 5\%$ .

## MAXIMUM RATINGS

Parameter	Min	Max	Units
Operating Temperature Range	-10	+50	°C
Storage Temperature Range	-45	+85	°C
Input Power Level		20	dBm
D. C. Voltage between Each Terminal		15	V

## PHYSICAL AND ENVIRONMENTAL CHARACTERISTICS

Parameter	Qualification Conditions
Life Testing	High temperature bake at +85 °C for 168 hours.
Temperature Cycling	MIL-STD 883, Method 1010: -40 °C to +85 °C, 10 cycles, 10 minutes dwell at temperature extremes
Vibration	MIL-STD-202, Method 201A: 10 to 55 Hz, double amplitude of 0.06" for 2 hours in each axis.
Mechanical Shock	MIL-STD-883, Method 2002, Test Condition B: 1500 g, 3 impacts each axis
Solder Heat Resistance and Reflow Condition	Peak temperature 240+/-5 °C for 10 seconds. Pre-heat: 150-170 °C for 60 to 90 seconds. Peak dwell: over 200 °C for 23 to 26 seconds. Handling: Class 1 per MIL-STD-1686 Reflow Profile is shown at the bottom of this table.
Lead Integrity	MIL-STD 883 Method 2004, Condition D 8 oz for 30 seconds.
Solderability	MIL-STD-883 Method 2003: 245 °C +/-5 °C; 95% coverage; no steam aging
Hermeticity	MIL-STD 883 Method 1014: Condition A2 and Condition C (no bomb)
ESD Classification	Class I per MIL-STD-883 Method 3015
Precautions	Do not subject devices to ultrasonic cleaning, which may cause deterioration and destruction of the device.



ISO 9001  
Registered

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